DORNPACKAGE

- Low Input Bias Current . . . 50 pA Typ
- Low Input Noise Current 0.01 pA/√Hz Typ
- Low Total Harmonic Distortion
- Low Supply Current . . . 8 mA Typ
- Gain Bandwidth . . . 3 MHz Typ
- High Slew Rate . . . 13 V/μs Typ
- Pin Compatible With the LM348

(TOP VIEW) **10UT** 14∏ 40UT 1IN - 2 13 4IN-1IN+∏ 3 Π 4IN + 12 V_{CC+} 4 IJ∨_{CC} – 2IN+[] 5 10 ¶ 3IN+ 2IN-∏ 6 9∏3IN-8 🛮 30UT 20UT 🛛

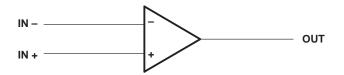
description

These devices are low-cost, high-speed, JFET-input operational amplifiers. They require low supply current yet maintain a large gain-bandwidth product and a fast slew rate. In addition, their matched high-voltage JFET inputs provide very low input bias and offset current.

The LF347 and LF347B can be used in applications such as high-speed integrators, digital-to-analog converters, sample-and-hold circuits, and many other circuits.

The LF347 and LF347B are characterized for operation from 0°C to 70°C.

symbol (each amplifier)



AVAILABLE OPTIONS

	Viemov	PACKAGE					
T _A	V _{IO} max AT 25°C	SMALL OUTLINE (D)	PLASTIC DIP (N)				
0°C to 70°C	10 mV	LF347D	LF347N				
0010700	5 mV	LF347BD	LF347BN				

The D packages are available taped and reeled. Add R suffix to the device type (e.g., LF347DR).

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC +}	18 V
Supply voltage V _{CC}	18 V
Differential input voltage, V _{ID}	±30 V
Input voltage, V _I (see Note 1)	±15 V
Duration of output short circuit	unlimited
Continuous total power dissipation	See Dissipation Rating Table
Operating temperature range	0°C to 70°C
Storage temperature range	65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

NOTE 1: Unless otherwise specified, the absolute maximum negative input voltage is equal to the negative power supply voltage.



SLOS013B - MARCH 1987 - REVISED AUGUST 1994

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{\scriptsize A}} \leq 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR	DERATE ABOVE T _A	T _A = 70°C POWER RATING
D	608 mW	7.6 mW/°C	61°C	608 mW
N	680 mW	N/A	N/A	680 mW

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V _{CC +}	3.5	18	V
Supply voltage, V _{CC} _	-3.5	-18	V

electrical characteristics over operating free-air temperature range, $V_{\text{CC}\pm}$ = ± 15 V (unless otherwise specified)

PARAMETER		_ +		LF347			LF347B		LIAUT
		TAI	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
Input offcot voltage	$V_{IC} = 0,$	25°C		5	10		3	5	mV
input onset voltage	$R_S = 10 \text{ k}\Omega$	Full range			13			7	IIIV
Average temperature coefficient of input offset voltage	$V_{IC} = 0,$ R _S = 10 k Ω			18			18		μV/°C
hand effect summed.	V:= - 0	25°C		25	100		25	100	pА
input offset current+	AIC = 0	70°C			4			4	nA
hand him amount t	V:0 - 0	25°C		50	200		50	200	pА
Input bias current+	AIC = 0	70°C			8			8	nA
Common-mode input voltage range			±11	-12 to		±11	-12 to		V
Maximum peak output voltage swing	R _L = 10 kΩ		±12	±13.5		±12	±13.5		V
l anno signal differential college	$V_{O} = \pm 10 \text{ V},$	25°C	25	100		50	100		\//m\/
Large-signal differential voltage	$R_L = 2 k\Omega$	Full range	15			25			V/mV
Input resistance	T _A = 25°C			1012			1012		Ω
Common-mode rejection ratio	$R_S \le 2 k\Omega$		70	100		80	100		dB
Supply-voltage rejection ratio	See Note 2		70	100		80	100		dB
Supply current				8	11		8	11	mA
	Input offset voltage Average temperature coefficient of input offset voltage Input offset current‡ Input bias current‡ Common-mode input voltage range Maximum peak output voltage swing Large-signal differential voltage Input resistance Common-mode rejection ratio Supply-voltage rejection ratio		$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	PARAMETER CONDITIONS TA^{\dagger} MIN TYP MAX MIN Input offset voltage $V_{IC} = 0$, $R_S = 10 \text{ k}Ω$ Full range 13 13 Average temperature coefficient of input offset voltage $V_{IC} = 0$, $R_S = 10 \text{ k}Ω$ 18 18 Input offset current‡ $V_{IC} = 0$ 25°C 25 100 Input bias current‡ $V_{IC} = 0$ 25°C 50 200 Input bias current‡ $V_{IC} = 0$ 70°C 8 Common-mode input voltage range ±11 to ±11 Maximum peak output voltage swing $R_L = 10 \text{ k}Ω$ ±12 ±13.5 ±12 Large-signal differential voltage $V_O = \pm 10 \text{ V}$, $R_L = 2 \text{ k}Ω$ Full range 15 50 Input resistance $T_A = 25^{\circ}C$ 70 100 80 Supply-voltage rejection ratio See Note 2 70 100 80	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$

[†] Full range is 0°C to 70°C.

operating characteristics, $V_{CC\pm}$ = $\pm 15~V$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{O1} /V _{O2}	Crosstalk attentuation	f = 1 kHz		120		dB
SR	Slew rate		8	13		V/μs
B ₁	Unity-gain bandwidth			3		MHz
V _n	Equivalent input noise voltage	$f = 1 \text{ kHz}, R_S = 20 \Omega$		18		nV/√ Hz
In	Equivalent input noise current	f = 1 kHz		0.01		pA/√Hz



[‡] Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive. Pulse techniques must be used that will maintain the junction temperatures as close to the ambient temperature as possible.

NOTE 2: Supply-voltage rejection ratio is measured for both supply magnitudes increasing or decreasing simultaneously.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
LF347BD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347BDE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347BDG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347BDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347BDRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347BDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347BN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LF347BNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LF347D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LF347N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
LF347NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

23-Apr-2007

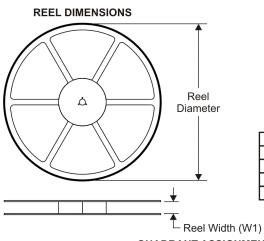
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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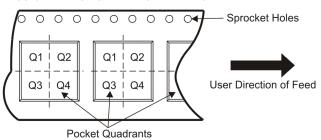
TAPE AND REEL INFORMATION





	Α0	Dimension designed to accommodate the component width
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
Г	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LF347BDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LF347DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



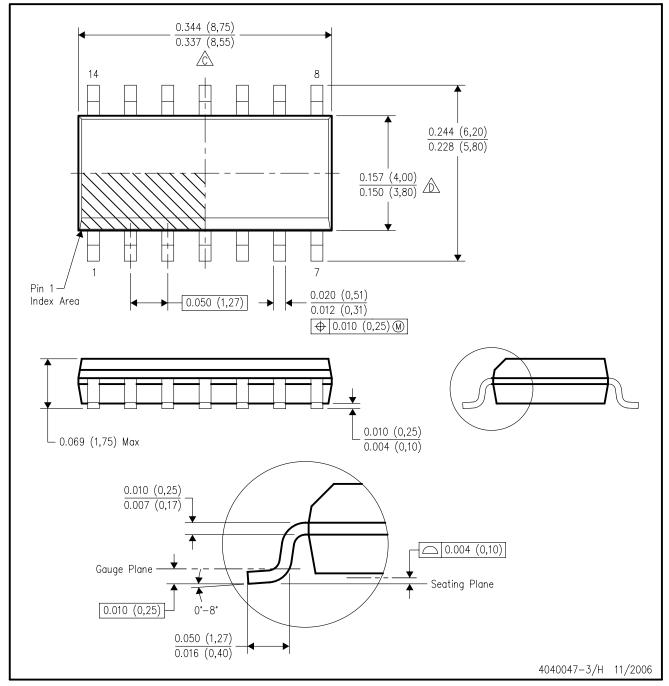


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LF347BDR	SOIC	D	14	2500	333.2	345.9	28.6
LF347DR	SOIC	D	14	2500	333.2	345.9	28.6

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

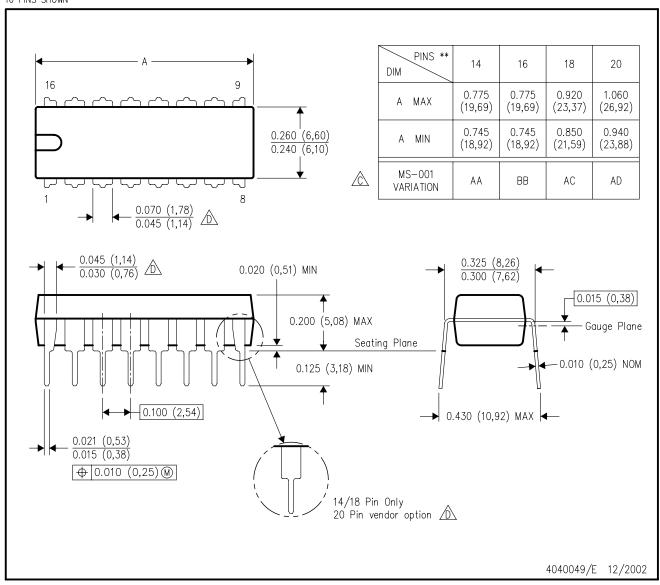
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

